

# SOT793-1

plastic thermal enhanced thin shrink small outline package;  
56 leads; body width 6.1 mm; exposed die pad

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HTSSOP56
<b>Package type industry code</b>	HTSSOP56
<b>Package style descriptive code</b>	HTSSOP (thermal enhanced thin shrink small outline package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	143E36T
<b>JEDEC package outline code</b>	MO-153
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	4-3-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	13.9	-	14	14.1	mm
E	package width	6	-	6.1	6.2	mm
A	seated height	[tbd]	-	1.1	1.1	mm
A <sub>2</sub>	package height	0.8	-	0.9	1.05	mm
n <sub>2</sub>	actual quantity of termination	-	-	56	-	

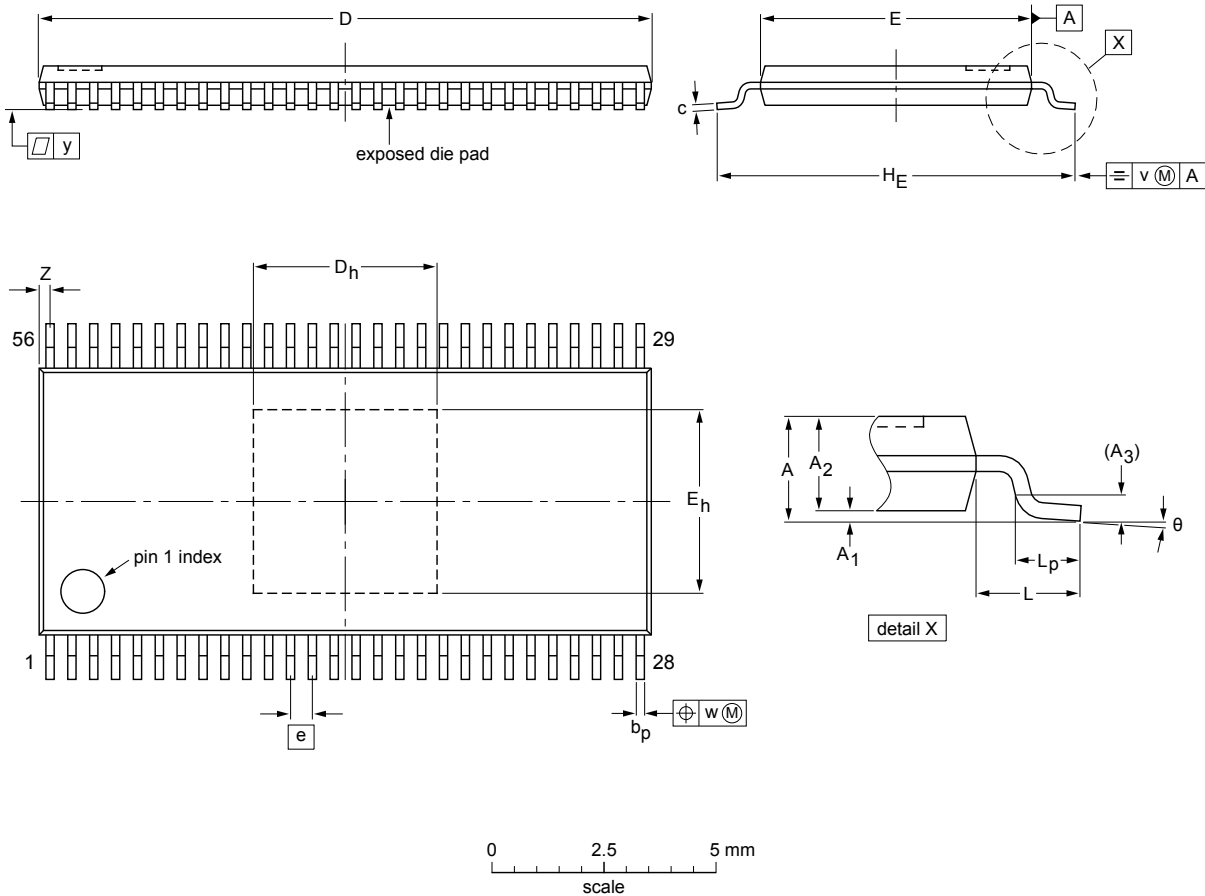


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2. Package outline

HTSSOP56: plastic thermal enhanced thin shrink small outline package; 56 leads; body width 6.1 mm; exposed die pad

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(2)</sup>	E <sub>h</sub>	e	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sup>(1)</sup>	θ
mm	1.2	0.15 0.05	1.05 0.80	0.25	0.27 0.17	0.20 0.09	14.1 13.9	4.3 4.1	6.2 6.0	4.3 4.1	0.5	8.3 7.9	1	0.8 0.4	0.2	0.08	0.1	0.4 0.1	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT793-1	143E36T	MO-153			03-03-04

Fig. 1. Package outline HTSSOP56 (SOT793-1)

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### 3. Soldering

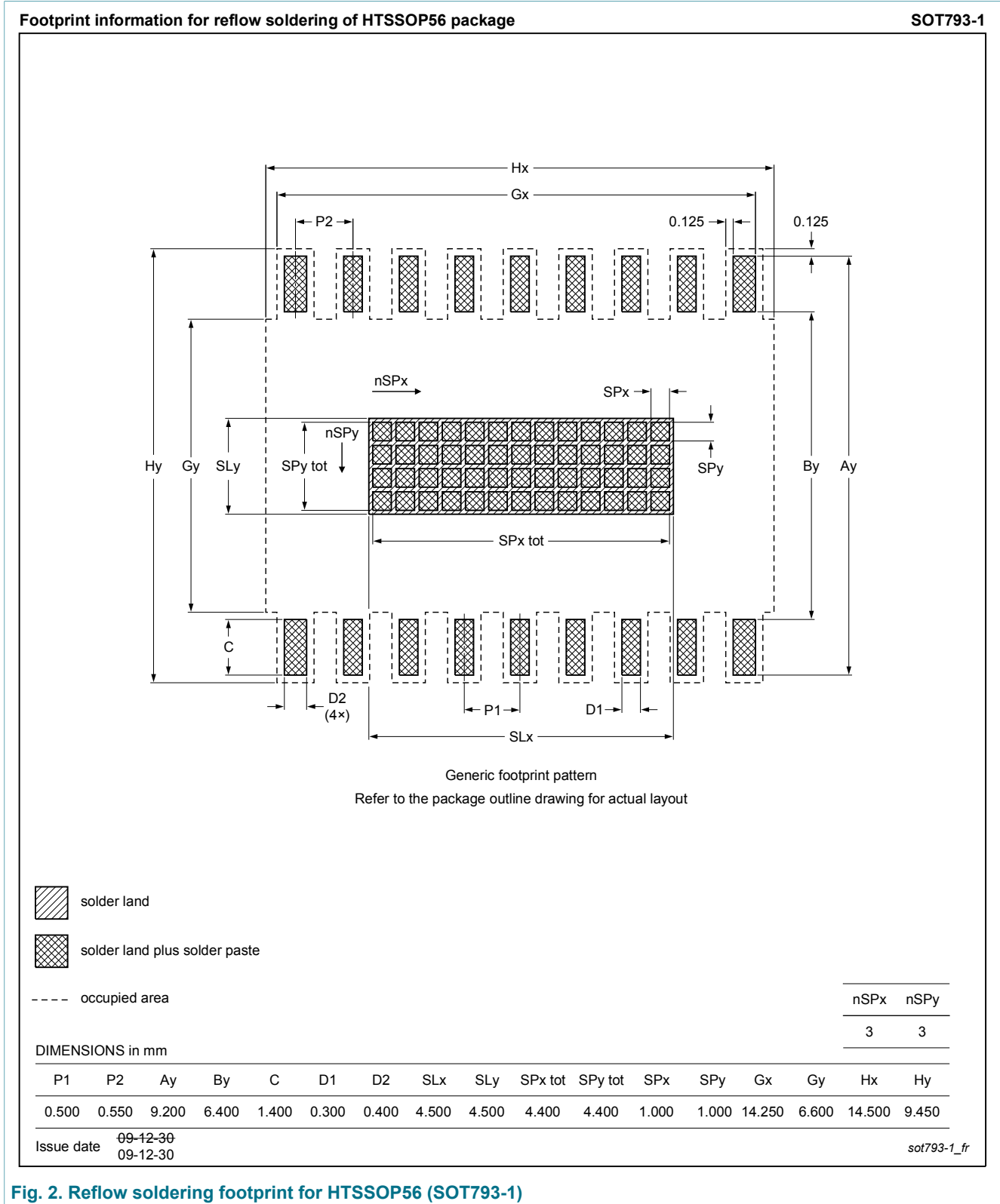


Fig. 2. Reflow soldering footprint for HTSSOP56 (SOT793-1)

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## 4. Legal information

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Date of release: 8 February 2016

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